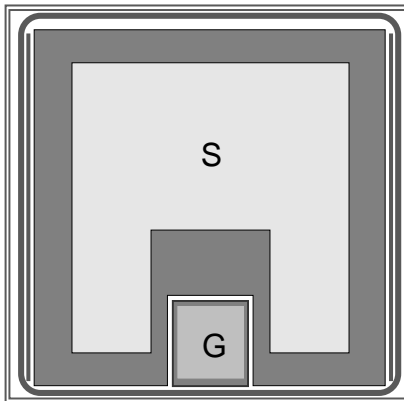


VF32



Backside: Drain

All dimensions in mils.

Die Geometry	Dimensions			Backside Metal	Bonding Pads <sup>2</sup>		Recommended Assembly Material		
	Length <sup>1</sup>	Width <sup>1</sup>	Thickness		Material	Size	Wire <sup>3</sup>	Wire Size <sup>3</sup>	Preform
VF32	55	55	11 ± 1.5	Au	Al-Cu-Si	4 x 4	Al	1.5	Epoxy

**Notes:**

1. Maximum values
2. Al-Cu-Si is used for higher operating current densities. Bond pad size represents smaller gate pad.
3. Bond wire size and material depends on AuTCB, TSB or Al USB.

11/19/02